

1. General description

AC Thyristor power switch in a SOT54 plastic package with self-protective capabilities against low and high energy transients

2. Features and benefits

- Exclusive negative gate triggering
- Full cycle AC conduction
- Remote gate separates the gate driver from the effects of the load current
- Very high noise immunity
- Safe clamping of low energy over-voltage transients
- Self-protective turn-on during high energy voltage transients

3. Applications

- Fan motor circuits
- Pump motor circuits
- Lower-power highly inductive, resistive and safety loads

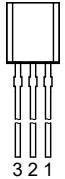
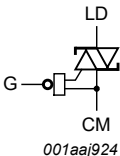
4. Quick reference data

Table 1. Quick reference data

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------------------------|-----------------------------------|--|-----|-----|-----|------|
| V_{DRM} | repetitive peak off-state voltage | | - | - | 600 | V |
| $I_{T(RMS)}$ | RMS on-state current | full sine wave; $T_{lead} \leq 71\text{ }^{\circ}\text{C}$; Fig. 1 | - | - | 0.8 | A |
| Static characteristics | | | | | | |
| I_{GT} | gate trigger current | $V_D = 12\text{ V}$; $I_T = 100\text{ mA}$; LD+ G-; $T_j = 25\text{ }^{\circ}\text{C}$; Fig. 6 | 1 | - | 10 | mA |
| | | $V_D = 12\text{ V}$; $I_T = 100\text{ mA}$; LD- G-; $T_j = 25\text{ }^{\circ}\text{C}$; Fig. 6 | 1 | - | 10 | mA |

5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|-----|--------|-------------|--|--|
| 1 | CM | common |  <p>TO-92 (SOT54)</p> |  <p>001aaJ924</p> |
| 2 | G | gate | | |
| 3 | LD | load | | |

6. Ordering information

Table 3. Ordering information

| Type number | Package | | |
|-------------|---------|---|---------|
| | Name | Description | Version |
| ACT108-600E | TO-92 | plastic single-ended leaded (through hole) package; 3 leads | SOT54 |

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|--------------|--------------------------------------|---|-----|------|------------------------|
| V_{DRM} | repetitive peak off-state voltage | | - | 600 | V |
| $I_{T(RMS)}$ | RMS on-state current | full sine wave; $T_{lead} \leq 71\text{ }^{\circ}\text{C}$; Fig. 1 | - | 0.8 | A |
| I_{TSM} | non-repetitive peak on-state current | full sine wave; $T_{j(init)} = 25\text{ }^{\circ}\text{C}$; $t_p = 20\text{ ms}$; Fig. 2 ; Fig. 3 | - | 13 | A |
| | | full sine wave; $T_{j(init)} = 25\text{ }^{\circ}\text{C}$; $t_p = 16.7\text{ ms}$ | - | 14.3 | A |
| I^2t | I^2t for fusing | $t_p = 10\text{ ms}$; SIN | - | 0.32 | A^2s |
| di_T/dt | rate of rise of on-state current | $I_G = 20\text{ mA}$ | - | 100 | $\text{A}/\mu\text{s}$ |
| I_{GM} | peak gate current | $t = 20\text{ }\mu\text{s}$ | - | 1 | A |
| V_{GM} | peak gate voltage | positive applied gate voltage | - | 15 | V |
| $P_{G(AV)}$ | average gate power | over any 20 ms period | - | 0.1 | W |
| T_{stg} | storage temperature | | -40 | 150 | $^{\circ}\text{C}$ |
| T_j | junction temperature | | - | 125 | $^{\circ}\text{C}$ |
| V_{PP} | peak pulse voltage | $T_j = 25\text{ }^{\circ}\text{C}$; non-repetitive, off-state; ten pulses on each voltage polarity; 20s or more between successive pulses;; Fig. 4 | - | 2.5 | kV |

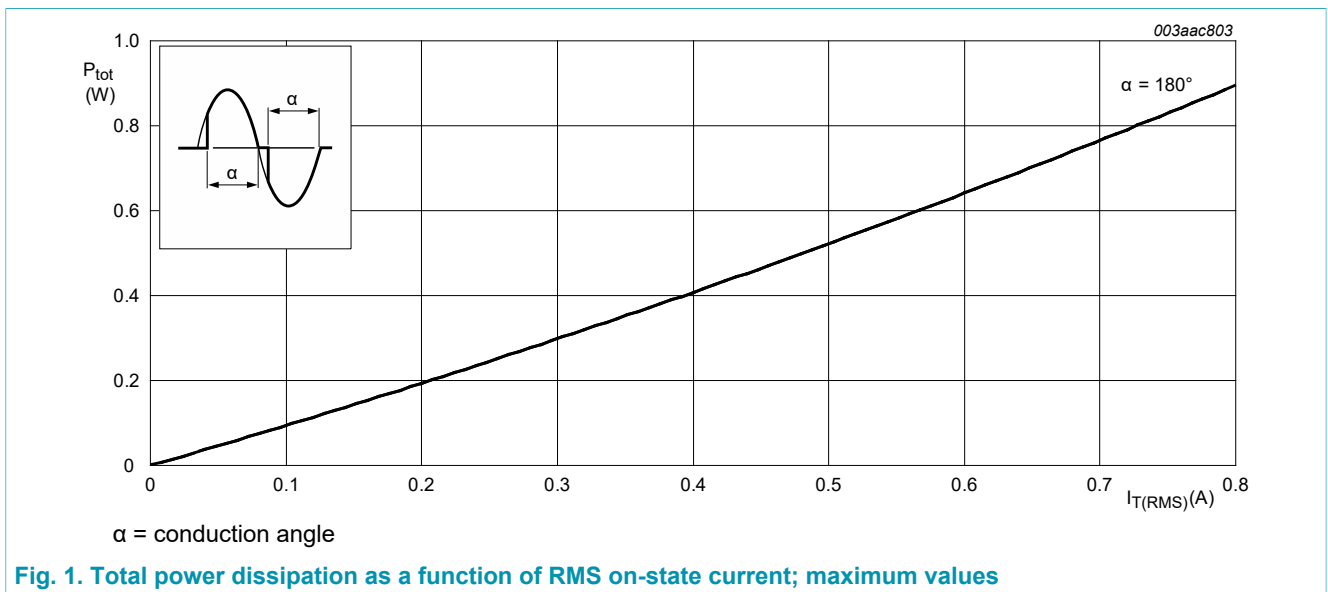


Fig. 1. Total power dissipation as a function of RMS on-state current; maximum values

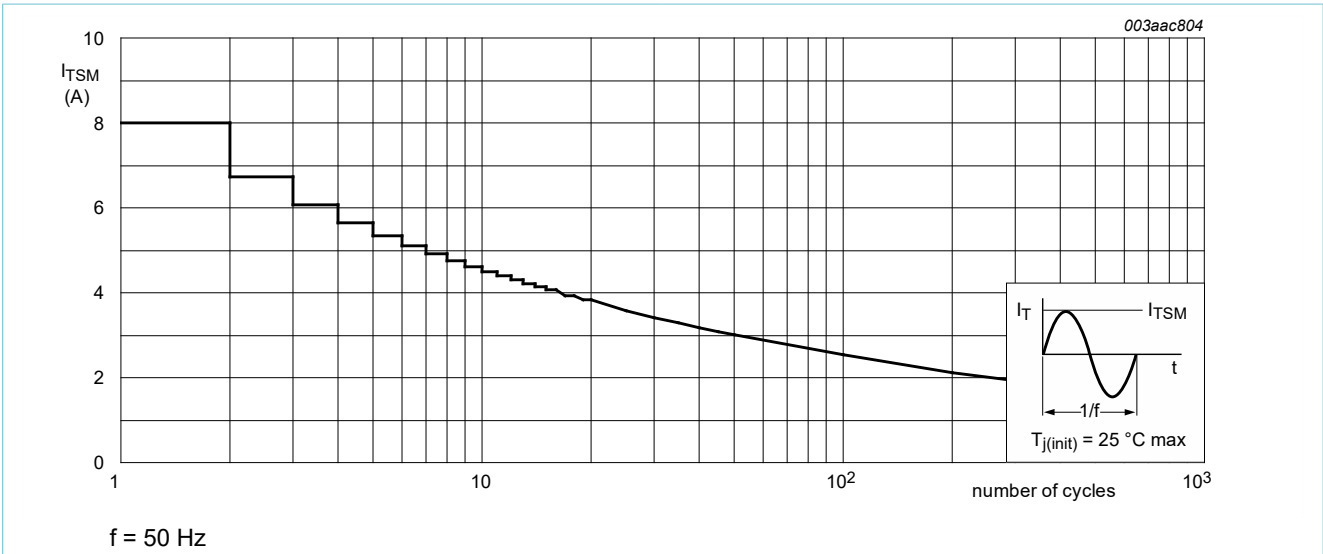


Fig. 2. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

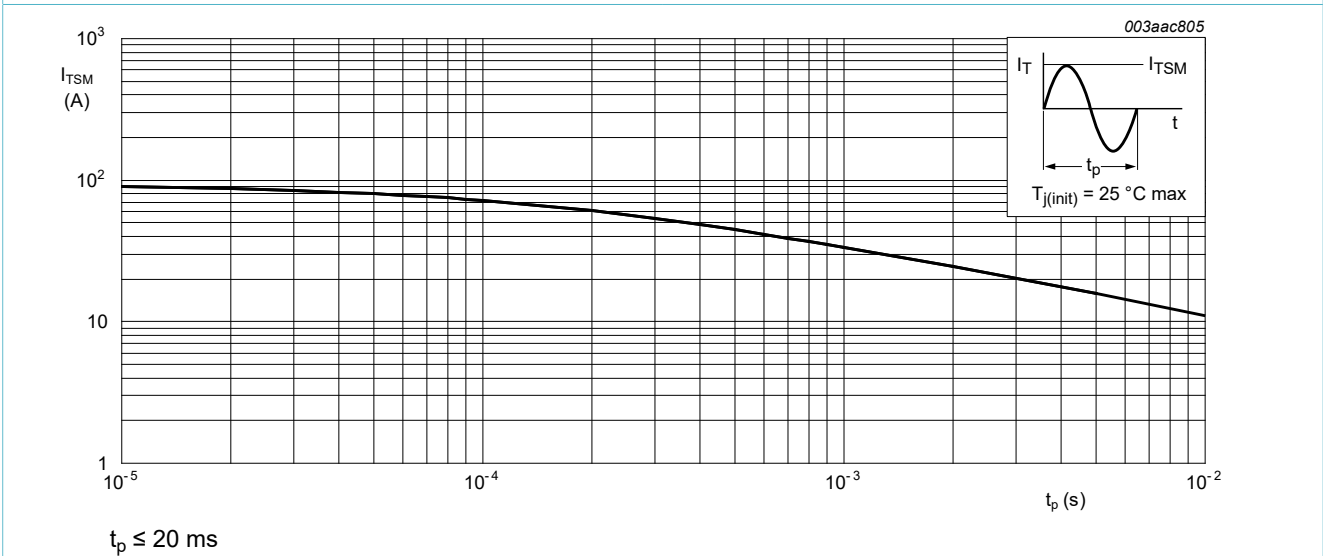


Fig. 3. Non-repetitive peak on-state current as a function of pulse width; maximum values

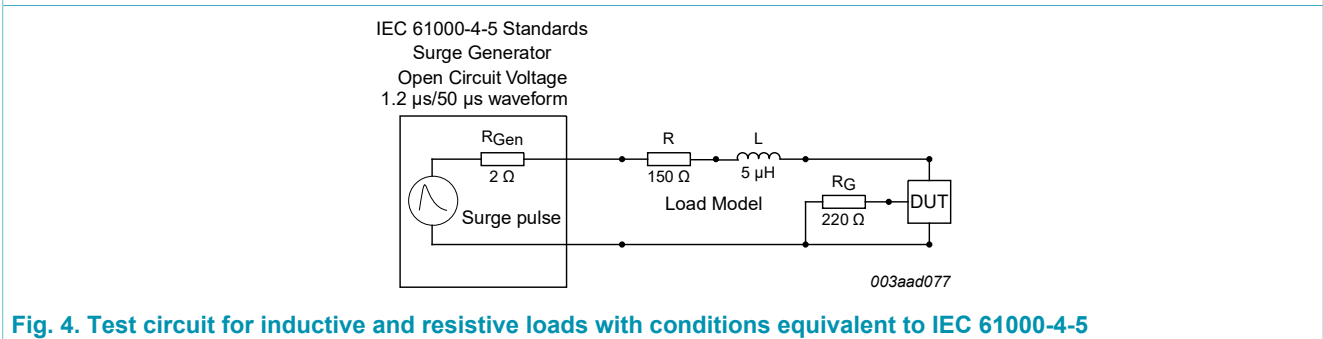


Fig. 4. Test circuit for inductive and resistive loads with conditions equivalent to IEC 61000-4-5

8. Thermal characteristics

Table 5. Thermal characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|------------------|--|---|-----|-----|-----|------|
| $R_{th(j-lead)}$ | thermal resistance from junction to lead | full cycle with heatsink compound; Fig. 5 | - | - | 60 | K/W |
| $R_{th(j-a)}$ | thermal resistance from junction to ambient free air | full cycle; printed-circuit board mounted; lead length 4 mm | - | 150 | - | K/W |

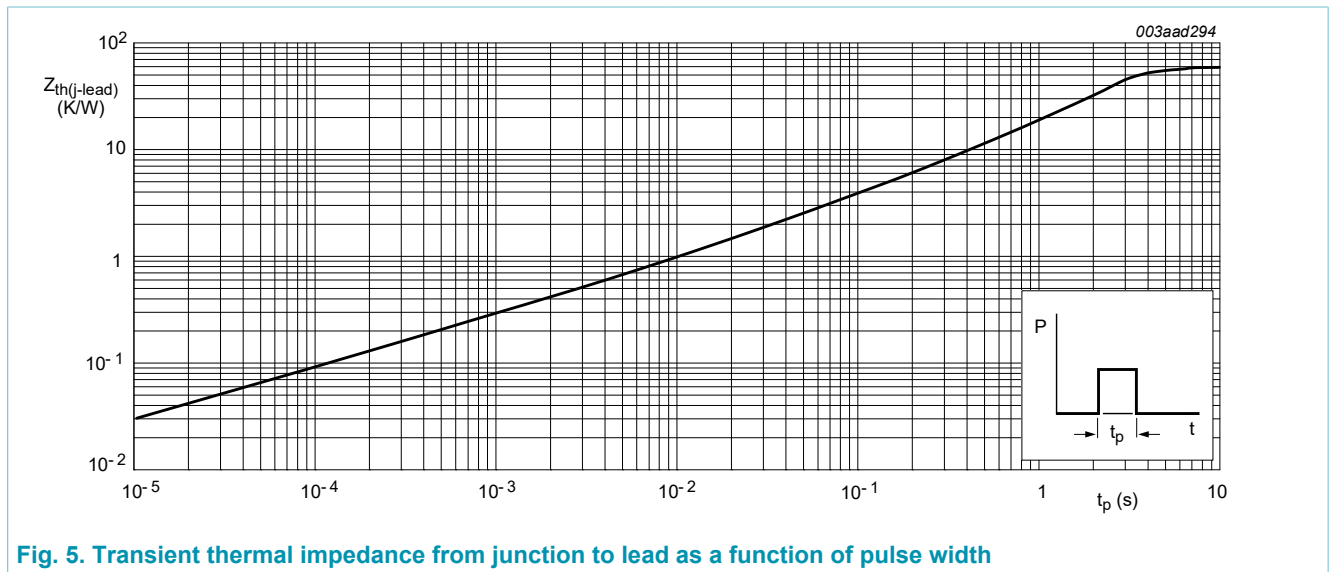


Fig. 5. Transient thermal impedance from junction to lead as a function of pulse width

9. Characteristics

Table 6. Characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--------------------------------|---------------------------------------|--|------|-----|-----|------|
| Static characteristics | | | | | | |
| I _{GT} | gate trigger current | V _D = 12 V; I _T = 100 mA; LD+ G-; T _j = 25 °C; Fig. 6 | 1 | - | 10 | mA |
| | | V _D = 12 V; I _T = 100 mA; LD- G-; T _j = 25 °C; Fig. 6 | 1 | - | 10 | mA |
| I _L | latching current | V _D = 12 V; I _G = 100 mA; LD+ G-; T _j = 25 °C; Fig. 7 | - | - | 25 | mA |
| | | V _D = 12 V; I _G = 100 mA; LD- G-; T _j = 25 °C; Fig. 7 | - | - | 20 | mA |
| I _H | holding current | V _D = 12 V; T _j = 25 °C; Fig. 7 | - | - | 20 | mA |
| V _T | on-state voltage | I _T = 1.1 A; T _j = 25 °C; Fig. 8 | - | - | 1.3 | V |
| V _{GT} | gate trigger voltage | V _D = 400 V; I _T = 100 mA; T _j = 125 °C | 0.15 | - | - | V |
| | | V _D = 12 V; I _T = 100 mA; T _j = 25 °C | - | - | 1 | V |
| I _D | off-state current | V _D = 600 V; T _j = 25 °C | - | - | 2 | μA |
| | | V _D = 600 V; T _j = 125 °C | - | - | 0.2 | mA |
| V _{CL} | clamping voltage | I _{CL} = 0.1 mA; t _p = 1 ms; T _j = 25 °C; Fig. 9 | 650 | - | - | V |
| Dynamic characteristics | | | | | | |
| dV _D /dt | rate of rise of off-state voltage | V _{DM} = 402 V; T _j = 125 °C; (V _{DM} = 67% of V _{DRM}); exponential waveform; gate open circuit; Fig. 10 | 2000 | - | - | V/μs |
| di _{com} /dt | rate of change of commutating current | V _D = 400 V; T _j = 125 °C; I _{T(RMS)} = 0.8 A; dV _{com} /dt = 20 V/μs; (snubberless condition); gate open circuit; Fig. 11 ; Fig. 12 | 0.5 | - | - | A/ms |

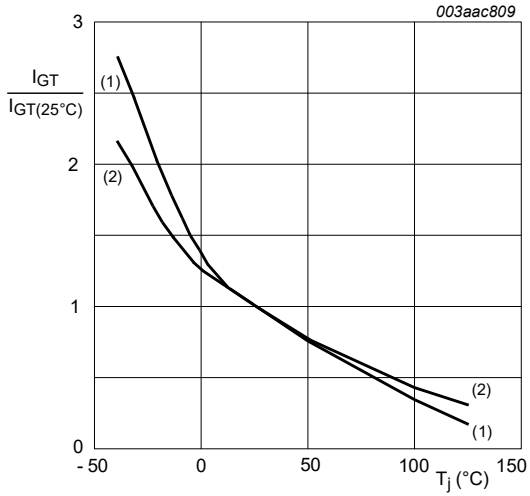


Fig. 6. Normalized gate trigger current as a function of junction temperature

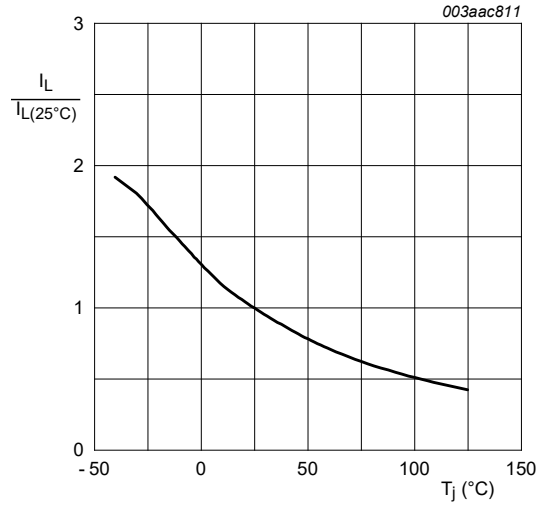
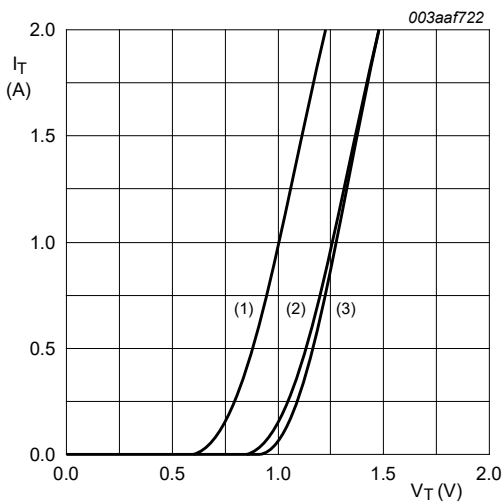


Fig. 7. Normalized latching current as a function of junction temperature



$V_o = 0.758 \text{ V}; R_s = 0.263 \Omega$
 (1) $T_j = 125^{\circ}\text{C}$; typical values
 (2) $T_j = 125^{\circ}\text{C}$; maximum values
 (3) $T_j = 25^{\circ}\text{C}$; maximum values

Fig. 8. On-state current as a function of on-state voltage

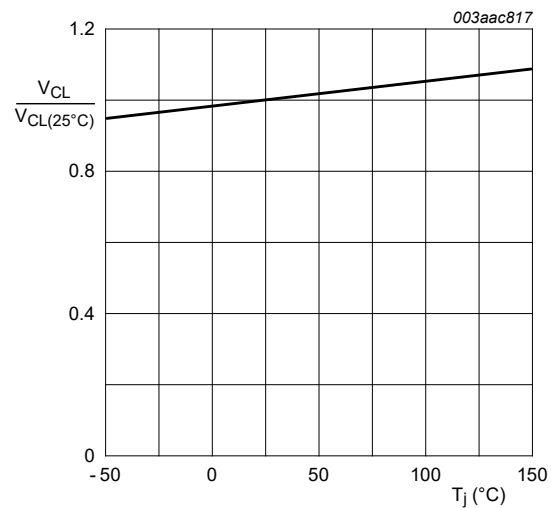
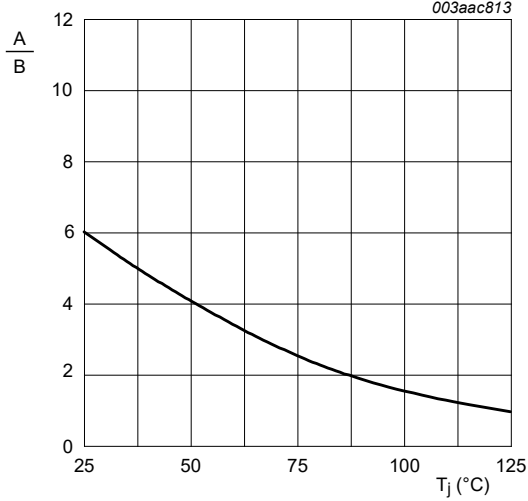
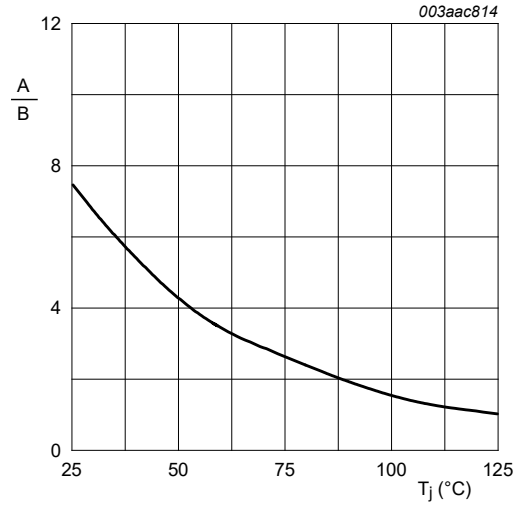


Fig. 9. Normalized clamping voltage (upper limit) as a function of junction temperature; minimum values



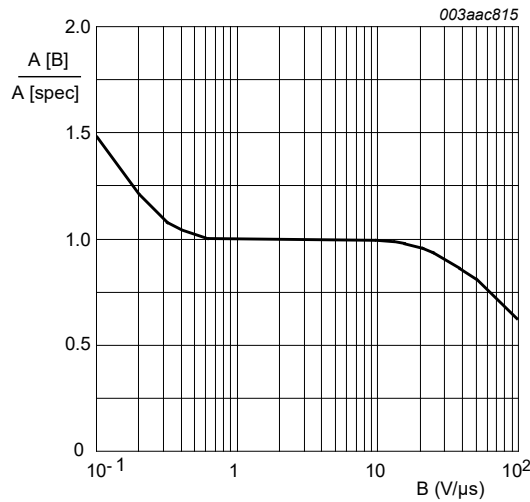
A = dV_D/dt at condition T_j °C
 B = dV_D/dt at condition T_j [125] °C

Fig. 10. Normalized rate of rise of off-state voltage as a function of junction temperature



A = di_{com}/dt at condition T_j °C
 B = di_{com}/dt at condition T_j [125] °C
 $V_D = 400$ V

Fig. 11. Normalized critical rate of rise of commutating current as a function of junction temperature



A [B] = di_{com}/dt at condition B, dV_{com}/dt
 A [spec] is the data sheet value for di_{com}/dt
 turn-off time is less than 20 ms

Fig. 12. Normalized critical rate of change of commutating current as a function of critical rate of change of commutating voltage; minimum values

10. Package outline

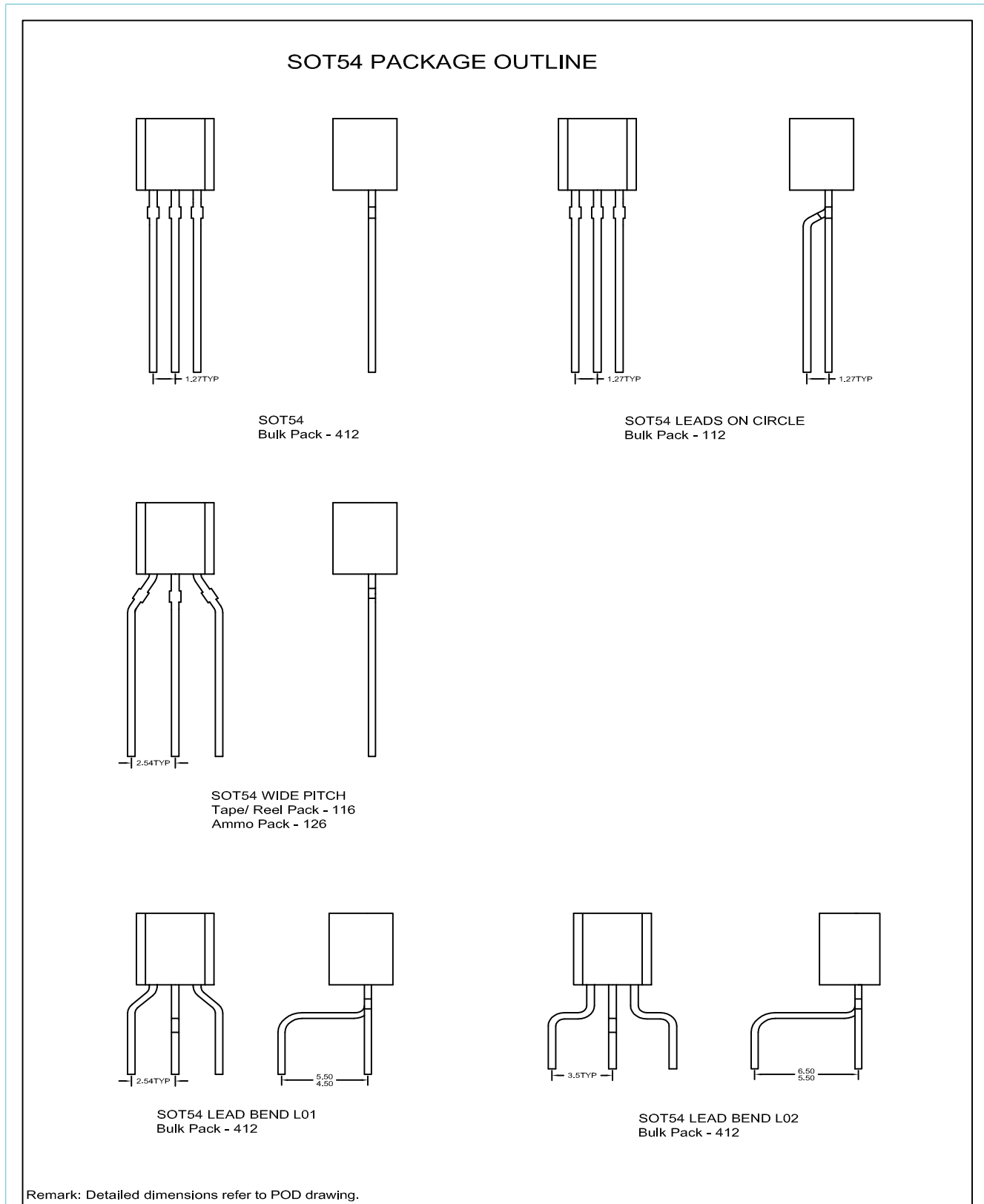


Fig. 13. Package outline TO-92 (SOT54)

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|--------------------------------|--------------------|---|
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